

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE4998S8	**Issued**	02. April 2021
MA#	MA001317790		
Package	PG-TDSO-8-1	**Weight***	66.82 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.926	2.88	2.88	28818	28818
leadframe	non noble metal	zinc	7440-66-6	0.062	0.09		926	
	non noble metal	tin	7440-31-5	0.077	0.12		1158	
	non noble metal	chromium	7440-47-3	0.093	0.14		1389	
	non noble metal	copper	7440-50-8	30.717	45.97	46.32	459671	463144
wire	noble metal	gold	7440-57-5	0.058	0.09	0.09	874	874
encapsulation	organic material	carbon black	1333-86-4	0.065	0.10		968	
	plastics	epoxy resin	-	3.494	5.23		52292	
	inorganic material	silicondioxide	60676-86-0	28.796	43.09	48.42	430927	484187
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7441	7441
plating	noble metal	silver	7440-22-4	0.793	1.19	1.19	11868	11868
glue	plastics	epoxy resin	-	0.061	0.09		917	
	plastics	acrylic resin	-	0.061	0.09		917	
	inorganic material	silicondioxide	60676-86-0	0.123	0.18	0.36	1834	3668
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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